

Copper Chalcogenide–Copper Tetrahedrite Composites—A New Concept for Stable Thermoelectric Materials Based on the Chalcogenide System

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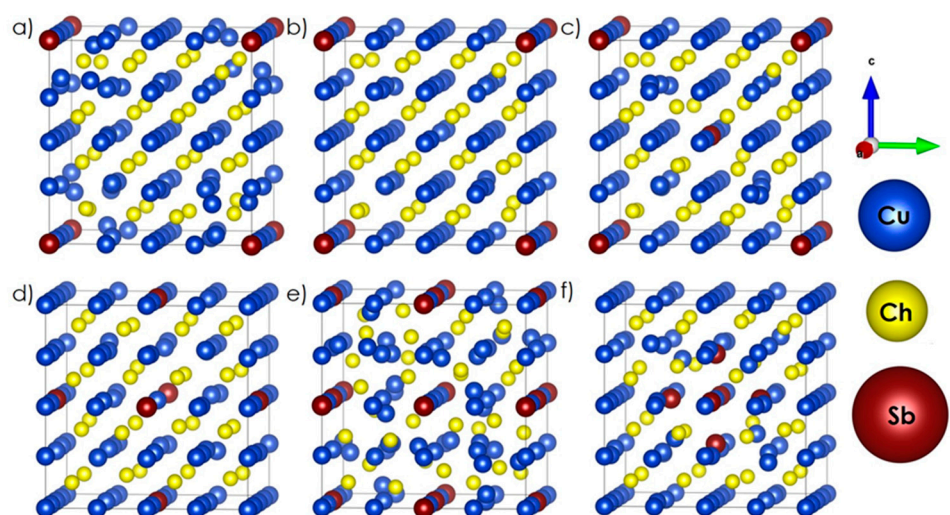


Figure S1. Optimized model structures: (a) Cu_{1.97}Sb_{0.03}Ch, (b) Cu_{1.94}Sb_{0.03}Ch, (c) Cu_{1.94}Sb_{0.06}Ch, (d) Cu_{1.85}Sb_{0.05}Ch, (e) Cu_{1.81}Sb_{0.19}Ch_v1, (f) Cu_{1.81}Sb_{0.19}Ch_v2.

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